

♦ STRUCTURE Silicon Monolithic Integrated Circuit

♦ PRODUCT DDC2<sup>TM</sup> DISPLAY ID ROM

♦ PART NUMBER BU9882-W Series

PART NUMBER	PACKAGE
BU9882-W	DIP14
BU9882F-W	SOP14
BU9882FV-W	SSOP14

♦ FEATURES For DDC2<sup>TM</sup>

2kbit (128word × 8bit × 2port) EEPROM Single power supply (2.5V ~ 5.5V) 100,000 erase/write cycles endurance

#### ♦ ABSOLUTE MAXIMUM RATING (Ta=25°C)

Parameter	Symbol	Rating		Unit
Supply Voltage	Vcc	−0.3 <b>~</b> 6.5		V
		950 (BU9882-W) *1		
Power Dissipation	Pd	450 (BU9882F-W)	*2	mW
		350 (BU9882FV-W)	*3	1
Storage Temperature	Tstg	-65 <b>~</b> 125		°C
Operating Temperature	Topr	-40 <b>~</b> 85		°C
Terminal Voltage	_	-0.3∼Vcc+1.0	*4	V

<sup>\*</sup> Degradation is done at 9.5mW/°C(\*1), 4.5mW/°C(\*2), 3.5mW/°C(\*3) for operation above 25°C

## ♦ RECOMMENDED OPERATING CONDITION

Parameter	Symbol	Rating	Unit
Supply Voltage	Vcc	2.5~5.5	٧
Input Voltage	VIN	0~Vcc+1.0	٧

Status of this document

The Japanese version of this document is the fomal specification.

A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document, formal version takes priority.

<sup>\*4</sup> Max 6.8V



♦ MEMORY CELL CHARACTERISTICS(Ta=25°C,Vcc=2.5~5.5V)

		Unit			
Parameter		Min.	Тур.	Max.	Unit
Write/Erase Cycle	*1	100,000	-	-	Cycle
Data Retention	*1	10	-	-	Year

OInitial Data: Memory array FFh \*1 Not 100% TESTED

♦ DC OPERATING CHARACTERISTICS

(Unless otherwise specified Ta=-40~85°C, Vcc=2.5~5.5V)

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Parameter	Symbol	Spe	cifica	tion	Unit	
T G/B/HCCCI	Oymbo.	Min.	Тур.	Max.		
"H" Input Voltage1	VIHI	2	-	-	٧	
"L" Input Voltage I	VIL1	-	-	0.8	٧	Vcc <b>≧</b> 4.0V
"L" Input Voltage2	VIL2	-	-	0.2Vcc	٧	Vcc <4.0V
"L" Output Voltage	VOL	-	-	0.4	٧	SDA_PC0/1, IOL=3.0mA +1
Input Leakage	ILIT	-1		1	μА	SCL_PC0/1, DDCENA, BANKSEL
Current1	ICII			. '	<u>"</u>	VIN=0V~Vcc+1.0
Input Leakage Current2	IL12	-1	-	50	μА	WPB
Output Leakage	ilo	-1		٠,	u A	SDA_PC0/1.SCL/SDA_MON(DDCENA=GND)
Current	ILO	-1	_	1	μΑ	VOUT=0V~Vcc+1.0
Operating Current	ICC	_	1.5	3	mA	fSCL=400kHz, Vcc=5.5V
Operating Current	100		1.3		l ma	tWR=10ms
						SCL/SDA_PC0/1=Vcc
Standby Current	ISB	_	0.1	5	L A	SCL/SDA_MON=High=Z
Scandby Gurrent	ISB	_	".1	"	" ^	DDCENA=WPB=BANKSEL=GND
						DUALPCB=Vcc

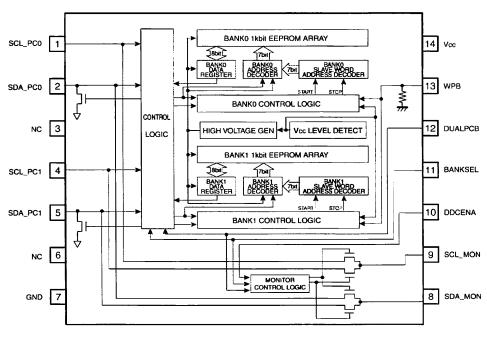
- OThis product is not designed for protection against radioactive rays.
- \*1 IOL at monitor mode (DDCENA=HIGH) is sum of current flowed from Pull up resistor on SDA\_MON Side, and Pull up resistance on SDA\_PC0/PC1.

# ♦ AC OPERATING CHARACTERISTICS

(Unless otherwise specified Ta=-40~85°C)

Parameter	Symbol	Fast−mode 2.5≦Vcc≨5.5V			Standard~mode 2.5≦Vcc≨5.5V			Unit
		Min.	Тур.	Max.	Min.	Тур.	Max.	1
Clock Frequency	fSCL	-	-	400	-	-	100	kHz
Data Clock High Period	tHIGH	0.6	-	-	40	-	-	μs
Data Clock Low Period	tLOW	1.3	_	-	47	-	-	μs
SDA and SCL Rise Time	tR	-	-	0.3	-	-	1.0	μs
SDA and SCL Fall Time	tF	-	-	0.3	-	-	0.3	μ s
Start Condition Hold Time	tHD:STA	0.6	-	-	4.0	-	-	μs
Start Condition Setup Time	tSU:STA	06	-	-	4.7	-	-	μs
Input Data Hold Time	tHD:DAT	0	-	-	0	-		tis
Input Data Setup Time	tSU:DAT	100	-	-	250	-	-	rs
Output Data Delay Time	tPD	-	-	0.9	-	-	3.5	μs
Stop Condition Setup Time	tSU:STO	0.6	-	-	4.0	-	-	μs
Bus Free Time	tBUF	1.3	-	-	4.7	-	-	μѕ
Write Cycle Time	tWR	-	-	10	-	-	10	ms
Noise Spike Width (SDA and SCL)	tl	-	-	01	-	-	0.1	μs

# ♦ BLOCK DIAGRAM



♦ PIN No./PIN NAME

PIN No.	PIN NAME
1	SCL_PC0
2	SDA_PC0
3	NC
4	SCL_PC1
5	SDA_PC1
6	NC
7	GND
8	SDA_MON
9	SCL_MON
10	DDCENA
11	BANKSEL
12	DUALPCB
13	WPB
14	Vcc

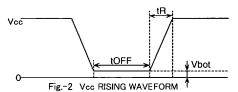
Fig.1 BLOCK DIAGRAM



#### **♦NOTES FOR POWER SUPPLY**

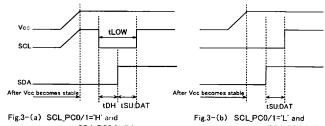
Vcc rises through the low voltage region in which internal circuit of IC and the controller are unstable, so that device may not work properly due to an incomplete reset of internal circuit. To prevent this, the device has the feature of P.O.R. and LVCC. In the case of power up, keep the following conditions to ensure functions of P.O.R. and LVCC.

- 1. It is necessary for SDA\_PC0 and SDA\_PC1 to be "HIGH", for SCL\_PC0 and SCL\_PC1 to be either "HIGH" or "LOW".
- 2. Follow the recommended conditions of tR, tOFF, Vbot for the function of P.O.R. during power up.



♦ Recommended conditions of tR, tOFF, Vbot					
tR	tOFF	Vbot			
Below 10ms	Above 10ms	Below 0.2V			
Below 100ms	Above 10ms	Below 0.1V			

- 3. Prevent SDA\_PC0, SDA\_PC1, SCL\_PC0 and SCL\_PC1 from being "High-Z". In case that condition 1. and/or 2. cannot be met, take following actions.
  - A) Unable to keep condition 1. (SDA\_PC0 is "LOW" during power up, for example.)
    - → Control SDA\_PC0 and SCL\_PC0 to be "HIGH" as figure below. It applies to SDA\_PC1 and SCL\_PC1 also.
  - B) Unable to keep condition 2.
    - → After power become stable, execute software reset.
  - C) Unable to keep both conditions 1 and 2.
    - → Follow the instruction A first, then the instruction B.



SDA\_PC0/1='L'

SDA PC0/1='L'

## **CAUTIONS ON USE**

(1) Absolute maximum ratings

If the absolute maximum ratings such as impressed voltage and operating temperature range and so forth are exceeded, LSI may be destructed. Do not impress voltage and temperature exceeding the absolute maximum ratings. In the case of fear exceeding the absolute maximum ratings, take physical safety countermeasures such as fuses, and see to it that conditions exceeding the absolute maximum ratings should not be impressed to LSI.

- (2) GND electric potential
  - Set the voltage of GND terminal lowest at any action condition. Make sure that each terminal voltages is lower than that of GND terminal.
- (3) Heat design
  - In consideration of permissible dissipation in actual use condition, carry out heat design with sufficient margin.
- (4) Terminal to terminal shortcircuit and wrong packaging
  - When to package LSI onto a board, pay sufficient attention to LSI direction and displacement. Wrong packaging may destruct LSI. And in the case of shortcircuit between LSI terminals and terminals and power source, terminal and GND owing to foreign matter, LSI may be destructed.
- (5) Strong electromagnetic field
  - Use in a strong electromagnetic field may cause malfunction, therefore, evaluated design sufficiently.



#### ♦ PHYSICAL DIMENSION

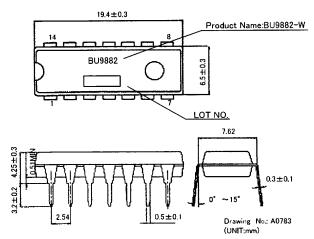


Fig.4-(a) PHYSICAL DIMENSION DIP14 (BU9882-W)

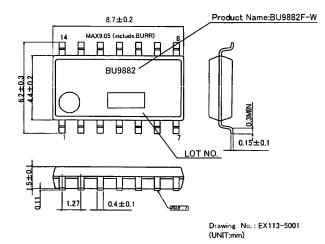


Fig.4-(b) PHYSICAL DIMENSION SOP14 (BU9882F-W)

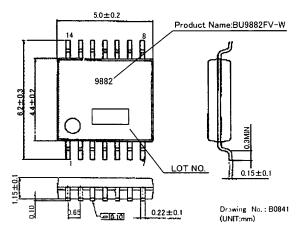


Fig.4-(c) PHYSICAL DIMENSION SSOP14(BU9882FV-W)

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